

January 2015

**Subject: TWENTY-FOURTH International Symposium
on
PROCESSING AND FABRICATION OF ADVANCED MATERIALS: XXIV**

Subject: A 'PERSONAL' INVITATION

Dear **Member of JIC**,

We, the organizers are truly pleased to announce the *International Symposium, the Twenty-Fourth in a series*, on **PROCESSING AND FABRICATION OF ADVANCED MATERIALS** to be held at **Kansai University in Suita, Osaka, JAPAN** during **December 18-20, 2015**. The symposium is primarily designed to bring together scientists, biologists, technologists, researchers, engineers and potential end-users of these exciting new and emerging materials to discuss recent advances, trends and opportunities for their application. **The subjects of the symposium session are neatly detailed in the homepage of PFAM 24 (URL: <http://pfam24.jp/>).**

I am **INVITING** you and members of your research group to attend the symposium and present **either an INVITED or CONTRIBUTED PAPER** of your research work in a relevant area that is specified in the home page. Please indicate your acceptance by submitting an abstract to the attention of any one of the four organizers between the time period **April 15, 2015 to July 15, 2015**. **A written version of your paper is required and/or essential (deadline for Submission: September 20, 2015) and will be published in the proceedings (bound volumes) of the symposium that will be made available at the meeting (December 18, 2015).** Instructions for manuscript preparation will be provided to all authors whose abstracts have been accepted for presentation at this intellectual event.

We eagerly look forward to your acceptance of my invitation and hope to see your participation, involvement and inclusion in the symposium proceedings (bound volumes).

Best regards.

Sincerely yours,

Dr. Masahiko Ikeda
Symposium Co-organizer
Kansai University, Japan

Dr. Takumi Haruna
Symposium Co-organizer
Kansai University, Japan

Dr. Mitsuo Niinomi
Symposium Co-organizer
Tohoku University, Japan

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Dr. T.S. Srivatsan
Symposium Co-Organizer
The University of Akron, USA

Cc. files